

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	25578	wafer near (chips or ics or integrated near circuits or dies or dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:11
L2	38	1 and conduct\$4 near interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:46
L3	393	conduct\$4 near interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:46
L4	22	3 and solder near mask\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:53
L5	226	3 and (mask\$1 or film\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:53
L6	214	5 and (hole\$1 or via\$1 or opening\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:54
L7	127	6 and bump\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:54
L8	119	7 and pad\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 14:55

L9	75	8 and test\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 15:06
L10	44	8 not 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 15:06